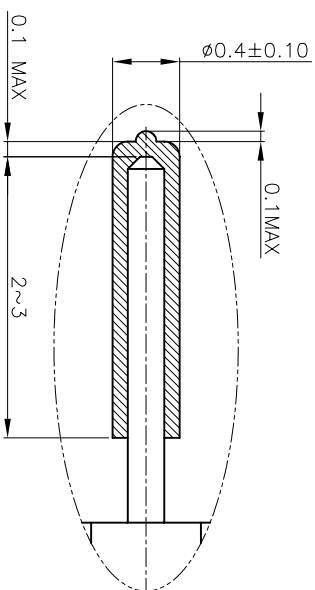
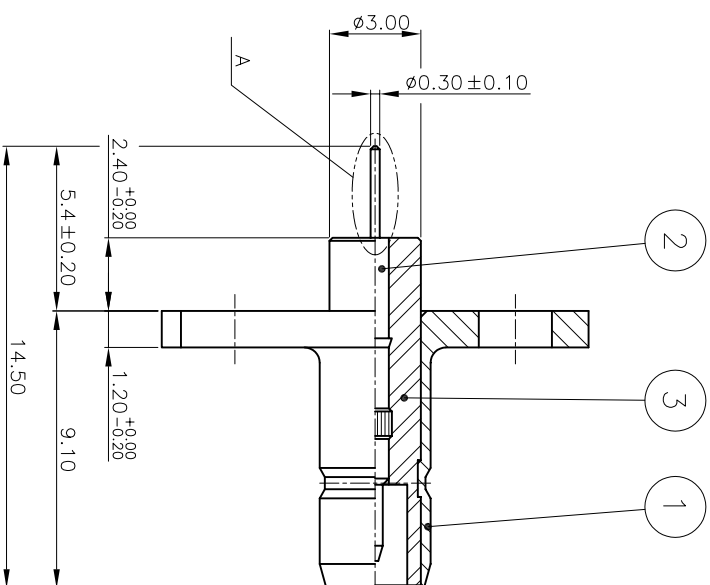
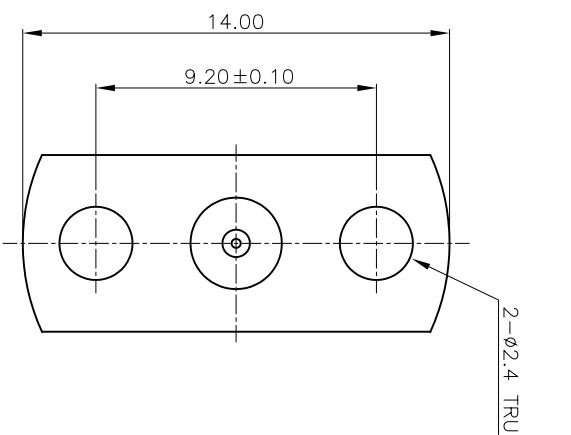


REVISION		
REV	DESCRIPTION	DATE
R	최초 개정	2009.07.09.



A부 DIPPING 작업 할 것

3	INSULATOR	1	TEFLON		DIN01608-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT02041-5/1
1	BODY	1	MBSBD	Nickel Plate	DBD02538-5/1
NO.	DESCRIPTION	QTY	MATERIAL	PLATING	CODE

DATE	2009. 07. 09.
APPROVED BY	S.J.YOUN
CHECKED BY	E.H.KIM
DRAWN BY	I.C.KIM

TOLERANCE	Decimal
Angle	±0.1°
±1°	

FINISH	SCALE	UNIT
	4/1	mm

KU COMTECH	RF & MICROWAVE TECHNOLOGY
KU COMTECH CO.,LTD.	Tel : 82-32-347-8015
	Fax : 82-32-347-8017

TITLE	DWG NO.	REVISION	SHEET
SMB50 SOLDER END JS-2H	CN02423-7/1	R	1 of 1